

REMARKS

This case has been carefully reviewed and analyzed in view of the Official Action dated June 21, 2005.

The Examiner has rejected claims 8-11 under 35 U.S.C. 103(a) as being unpatentable over Kuo (U.S. Patent number 6,637,585) in view of Bernreuther et al (U.S. Patent number 5,521,478). However, it is respectfully requested that the rejections be withdrawn in light of the following reasons.

The present invention resides in a transporting device for a vertical-type thin circuit board etching machine which utilizes a rail made of anti-corrosive rigid material to guide a lower edge of a circuit board thereby enabling very thin circuit boards to be transmitted smoothly through an etching machine. This feature is not shown in either Kuo (U.S. Patent number 6,637,585) or Bernreuther et al (U.S. Patent number 5,521,478). . Moreover, none of the cited references discloses or teaches a transporting device for a vertical-type thin circuit board etching machine comprising: a base plate including a flat plate and a rail mounted on said flat plate; a transmission shaft drivingly connected with an electric motor and provided with worm threads; a plurality of worm gears engaged with said worm threads of said transmission shaft; a plurality of vertical shafts each having an upper end engaged with a respective one of said worm gears, said vertical shafts each having a lower end extending downwardly into said flat plate; a plurality of support rollers mounted said vertical shafts; a plurality of soft transmission clip rollers each mounted on a lower end of a respective one of said vertical shafts, said soft transmission clip rollers being positioned above said rail; said flat plate being provided with a plurality of protruded shaft hole seats each adapted receiving said lower end of said vertical shafts; said rail being seamless and made of anti-corrosive rigid material; whereby when a circuit board is transmitted said soft transmission clip rollers, said circuit board will be

guided by said rail thereby enabling said circuit board to move smoothly along said rail without causing damage to a lower edge of said circuit board.

Accordingly, even if the cited references are combined together, the combined disclosure still fails to teach each and every element of the claimed invention and so the subject matter sought to be patented as a whole would not have been obvious to one of ordinary skill in the art.

The applicant has reviewed the prior art as cited by the Examiner but not used in the rejection and believes that the new claim clearly and distinctly patentably defines over such prior art.

It is now believed that the subject Patent Application has been placed in condition of allowance, and such action is respectfully requested.

Respectfully submitted,



Signature

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September 21, 2005